



Customer Information Notification

202607012I : New FS26 Product Offerings and Datasheet Update Rev 5.1 (30V Variant and Backend Manufacturing Site Expansions)

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 30, 2026 **Effective Date:** Jul 31, 2026

Dear Emma Tempest,

Here is your personalized communication about an NXP notification.
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Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Process	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Equipment	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling Location	☐ Test Location	☐ Electrical spec./Test coverage
☐ Firmware	☒ Other: Datasheet Update (New Orderable Part Numbers: 30V Variant and Backend Manufacturing Site Expansions)			

Notification Overview

Description

NXP Semiconductors announces an expansion of the FS26 family of Safety System Basis Chip devices to include products assembled at UTL (Bangkok, Thailand) and tested at NXP ATKL (Kuala Lumpur, Malaysia), along with a datasheet update to revision 5.1 for the products associated with this notification. The new UTL / ATKL products are offered in addition to the existing products manufactured at NXP ATTJ (Tianjin, China). To distinguish the new manufacturing flow, dedicated orderable part numbers have been created and added to the updated datasheet alongside their functionally equivalent ATTJ-manufactured counterparts. This manufacturing expansion and new product offerings support NXP's strategic objective to provide supply assurance and geographic diversity of manufacturing sources.

In addition to the backend site expansion, NXP also announces new part numbers that support a 30V maximum input voltage rating. The following new product variants are now available with the expanded voltage capability:

1. MFS2643HMDA0AD/R2
2. MFS2643HMBA0AD/R2
3. MFS2643HMDA0UD/R2
4. MFS2643HMBA0UD/R2

New FS26 datasheet revision 5.1 is available at the secure NXP site:

<https://www.nxp.com/webapp/sd/collateral/1785164846107735643307?version=5.1>

Please refer to the attached documentation and the revision history section of the updated datasheet for a detailed description of all changes.

Qualification activities supporting the addition of the UTL assembly site and NXP ATKL test site have been completed in accordance with NXP qualification requirements. Detailed qualification results and supporting documentation are available upon request through the Production Part Approval Process (PPAP) package.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

New FS26 products manufactured with UTL (Bangkok, Thailand) assembly and NXP ATKL (Kuala Lumpur, Malaysia) wafer test and final test are being introduced to provide supply assurance and geographic diversity of manufacturing sources. New FS26 30V product variants are introduced to support application use cases that require expanded input voltage capability.

Identification of Affected Products

New FS26 products with assembly at UTL (Bangkok, Thailand) and wafer test / final test at NXP ATKL (Kuala Lumpur, Malaysia) are identified by the part number suffix “UD.” This manufacturing flow is being added alongside the existing NXP ATTJ (Tianjin, China) manufacturing flow, which remains unchanged and is identified by the part number suffix “AD.”

Products manufactured through the UTL / ATKL flow can be distinguished by the assembly site code included in the trace code line of the top-side product marking. The assembly site code for UTL (Bangkok, Thailand) is “R”, while the assembly site code for existing ATTJ (Tianjin, China) is “CT.”

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new data sheet will be issued

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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